In the Claims

Claims 1 – 10 (Cancelled)

11. (New) An organic EL device manufacturing method comprising the steps of:

(a) positioning an integrated mask and a single substrate to be subjected to a deposition process in a deposition chamber using alignment marks formed on said integrated mask and said single substrate,

wherein said integrated mask comprises:

(a-1) a plurality of deposition masks each of which has an array of deposition apertures formed in accordance with a deposition pattern and alignment marks,

(a-2) a base plate which has a plurality of openings on which said deposition masks are arranged respectively,

(a-3) a plurality of engaging units provided on said base plate for engaging and disengaging each of said deposition masks, and

(a-4) said alignment marks formed on said base plate, and

wherein said integrated mask is fabricated by the steps of:

(a-5) detecting said alignment marks of said base plate and each of said deposition masks,

(a-6) adjusting the relative position between said base plate and each of said deposition masks by retaining and moving each of said deposition masks relative to said base plate, and

(a-7) retaining each of said deposition masks on said base plate using said engaging units after adjusting of said relative position; and

(b) patterning a thin film layer in said deposition process using said integrated mask, thereby forming n organic EL devices on said single substrate wherein n is an integer equal to or greater than 2.

12. (New) An organic EL device manufacturing method according to claim 11, wherein said integrated mask is set up by retaining m deposition masks on said base plate wherein m is an integer in the range of 2 to n.

13. (New) An organic EL device manufacturing method according to claim 12, wherein m and k satisfy $n = m \times k$ (k is an integer in the range of 2 to n).

14. (New) An organic EL device manufacturing method according to claim 11, wherein said thin film is an emitting layer or a metal electrode layer.